



Express Mail No. EV336673758US

Attorney Docket No. 108298630US
Disclosure No. 01-0532.00/US

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: SETHO SING FEE ET AL.
APPLICATION NO.: 09/944,246
FILED: 30 August 2001
FOR: PACKAGED MICROELECTRONIC
DEVICES AND METHODS OF FORMING
SAME

EXAMINER: TU TU V. HO
ART UNIT: 2818
CONFIRMATION NO.: 1798

Supplemental Information Disclosure Statement
As Submission Under 37 CFR §1.114

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

1. Timing of Submission

This information disclosure is being filed with a Request for Continued Examination under 37 CFR §1.114. The references listed on the enclosed Form PTO-1449 (modified) may be material to the examination of this application; the Examiner is requested to make them of record in the application.

2. Cited Information

Copies of the following references are enclosed:
 All cited references
 The following:

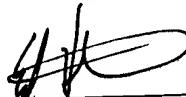
3. Effect of Information Disclosure Statement (37 CFR 1.97(h))

This Information Disclosure Statement is not to be construed as a representation that: (i) a search has been made; (ii) additional information material to the examination of this application does not exist; (iii) the information, protocols, results and the like reported by third parties are accurate or enabling; or (iv) the cited information is, or is considered to be, material to patentability. In addition, applicant does not admit that any enclosed item of information constitutes prior art to the subject invention and specifically reserves the right to demonstrate that any such reference is not prior art.

4. Fee Payment

No fees are believed due. However, should the Commissioner determine that fees are due in order for this Information Disclosure Statement to be considered, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 50-0665.

Respectfully submitted,
Perkins Coie LLP



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Date: 13 May 2004

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
Form PTO-1449 (Modified)
(Use several sheets if necessary)

Sheet

1

of

2

COMPLETE IF KNOWN	
Application Number	09/944,246
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First Named Inventor	Setho Sing Fee
Group Art Unit	2818
Examiner Name	Tu Tu V. Ho
Attorney Docket No.	108298630US

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No.	U.S. Patent or Application		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		NUMBER	Kind Code (if known)			
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		2004/0026773	A1	Koon et al.	02/12/2004	

OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume/issue number(s), publisher, city and/or country where published.		T
		ISHINO, Toshiaki, Silicone Adhesive Tape, Nitto Technical Report, Vol. 38, No. 2, pp. 49-50, December 2000, < http://www.nitto.com/rd/2000_2/15ishinoe.qxp.pdf >.		
		KUHNLEIN, Gerd, "A design and manufacturing solution for high reliable non-leaded CSP's like QFN," 2000 Electronics Packaging Technology Conference, pp. 169-175.		
		Tech Connect, QFN Leadframes, ASM Pacific Technology Ltd., pp. 10-14.		

EXAMINER	DATE CONSIDERED
*EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application(s).	



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	Siliconware Precision Industries Ltd., TSOP 1 (Thin Small Outline Package type1), 2 pages, retrieved from the Internet on June 26, 2003, < http://www.spil.com.tw/tsopi.html >.	
	Intersil, L56.8X8 56 Lead Quad Flat No-Lead Plastic Package, 1 page, December 2002, < http://www.intersil.com/data/pk/L56.8x8.pdf >.	

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